



Reliability Report

Report Title: AD8417-2 New Product Qualification

Report Number: 14650

Revision: B

Date: 21 December 2022



Summary

This report documents the successful completion of the reliability qualification requirements for the release of the AD8417-2 product in a 10-WLCSP package. The AD8417-2 is a high voltage, high resolution current sense amplifier and is composed of two side-by-side AD8417 dice with shorted biasing connections through RDL.

Table 1: AD8417-2 Product Characteristics

Die/Fab

Die Id	8YM80F03-IG
Die Size (mm)	1.92 x 1.01
Wafer Fabrication Site	ADI Limerick
Wafer Fabrication Process	0.35um DMOS
Approximate Transistor Count	5,480
Passivation Layer	HDPundoped
	oxide/Oxide&Nitride
Bond Pad Metal Composition	AlCu

Package/Assembly

Package	10-WLCSP		
Bump Pitch (mm)	0.35		
Bump Diameter (mm)	0.24		
Bumping Foundry	STATS		
RDL Layers	2		
RDL Composition	Ti(0.1)/Cu(0.2)/Cu(5)		
RDL Repassivation	Polyimide (7.5)/Polyimide (8.3)		
Under Bump Metallization	Ti(0.1)/Cu(0.2)/Cu(8.6)		
Bumping Process	Cu Bump/Redistribution		
Bump Composition	95.5Sn_4.0Ag_0.5Cu		
Moisture Sensitivity Level	1		
Maximum Peak Reflow Temperature (°C)	260		



Description / Results of Tests Performed

Tables 2 through 3 provide a description of the qualification tests conducted and the associated test results for products manufactured on the same technologies as described in Table 1. All devices were electrically tested before and after each stress. Any device that did not meet all electrical data sheet limits following stressing would be considered a valid (stress-attributable) failure unless there was conclusive evidence to indicate otherwise.

Table 2: WLCSP at STATS Package Qualification Test Results

Test Name	Specification	Conditions	Device	Lot #	Sample Size	Qty. Failures
High Temperature Storage Life (HTSL)	JESD22- A103	150°C, 1,000 Hours	AD8417-2	Q14650.HS1	77	0
Highly Accelerated	JESD22- A110	JESD22- 130C 85%RH AD45316	Q14917.HA1	32	0	
Temperature and Humidity		33.3 psia, Biased,	AD45510	Q14926.HA1x	32	0
Stress Test (HAST) 1		96 Hours	ADUCM413	Q13982.11	45	0
Temperature Cycling (TC)	JESD22- A104	-40°C/+125°C, 1	AD8417-2	Q14650.TC1	77	0
		Cycles/Hour,		Q14650.TC2	77	0
		1,000 Cycles		Q14650.TC3	77	0
		I Blased 1 ()()()	AD8417-2	Q14650.1.TH1	77	0
				Q14650.2.TH2	77	0
Temperature Humidity	JESD22-			Q14650.3.TH3	77	0
Bias (THB)	A101		ADP5202	Q14624.TH1	77	0
				Q14624.TH2	77	0
				Q14624.TH3	77	0
Unbiased HAST (UHST)	JESD22- A118	130C 85%RH	AD8417-2	Q14650.UH1	77	0
		33.3 psia, 96		Q14650.UH2	77	0
		Hours		Q14650.UH3	77	0

¹ These samples were subjected to preconditioning (per J-STD-020 Level 1) prior to the start of the stress test. Level 1 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 168 hrs @ 85°C, 85%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.



Table 3: 0.35µm DMOS at ADI-Limerick Fab Qualification Test Results

Test Name	Specification	Conditions	Device	Lot #	Sample Size	Qty. Failures
	MIL-STD- 883, M1015	125°C, 48 Hours	ADG5208F	Q11144.EL1a	600	0
			ADG5412F	Q10718.EL2a	200	0
			ADG5412F	Q10718.EL3a	200	0
Early Life Failure Rate (ELFR)				Q10083.27	87	0
(ELFK)	AEC-Q100- 008	Ta=150C, 48 Hours	AD8418W	Q10083.28	77	0
				Q10083.29	111	0
				Q10083.EL1	800	0
		150°C <tj<175°< td=""><td></td><td>Q10083.2</td><td>77</td><td>0</td></tj<175°<>		Q10083.2	77	0
High Temperature		C, Biased, 1,000	AD8418W	Q10083.5	77	0
Operating Life (HTOL) 1		Hours		Q10083.8	77	0
	IEODO0	125°C <tj<135°< td=""><td>AD8417-2</td><td>Q14984.1.HO1</td><td>77</td><td>0</td></tj<135°<>	AD8417-2	Q14984.1.HO1	77	0
	JESD22-	C, Biased, 1,000	AD5535B	Q12935.HO1b	77	0
10 1 -	A108	Hours	ADM1272	Q11624.35	77	0
High Temperature		4050 T: 45000		Q13046.26	77	0
Operating Life (HTOL) ²		135° <tj<150°c,< td=""><td>ADHV4702-1</td><td>Q13046.27</td><td>77</td><td>0</td></tj<150°c,<>	ADHV4702-1	Q13046.27	77	0
		1,000 Hours		Q13046.28	77	0
11: 1 T	IEODO0	45000 4 000	AD8417-2	Q14650.HS1	77	0
High Temperature Storage Life (HTSL)	JESD22- A103	150°C, 1,000 Hours	ADHV4702-1	Q13046.20	77	0
			AD5535C	Q13575.HS1	77	0
		130C 85%RH 33.3 psia, Biased, 96 Hours	AD8418W	Q10083.HA1	77	0
				Q10083.HA2	77	0
				Q10083.HA3	77	0
Highly Accelerated	150500		ADG5412F	Q11444.HA1	77	0
Temperature and Humidity	JESD22- A110			Q11444.HA2	77	0
Stress Test (HAST) 1				Q11444.HA3	77	0
,			ADHV4702-1	Q13046.4	77	0
				Q13046.5	77	0
				Q13046.6	77	0
Temperature Humidity Bias (THB)	JESD22- A101		AD8417-2	Q14650.1.TH1	77	0
				Q14650.2.TH2	77	0
				Q14650.3.TH3	77	0
		85°C, 85%RH, Biased, 1,000 Hours	AD5535B	Q13930.12	32	0
				Q13930.13	32	0
				Q13930.14	32	0
			AD5535B	Q12445.TH1	32	0
Temperature Humidity Bias				Q12445.TH2	32	0
(THB) ²				Q12445.TH3	32	0

¹ These samples were subjected to preconditioning (per J-STD-020 Level 1) prior to the start of the stress test. Level 1 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 168 hrs @ 85°C, 85%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.

Samples of the many devices manufactured with these package and process technologies are continuously undergoing reliability evaluation as part of the ADI Reliability Monitor Program. Additional qualification data is available on <u>Analog Devices' web site</u>.

² These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.



ESD Test Results

The results of Human Body Model (HBM) and Field-Induced Charged Device Model (FICDM) ESD testing are summarized in Table 4. ADI measures ESD results using stringent test procedures based on the specifications listed. Any comparison with another supplier's results should ensure that the same ESD test procedures have been used. For further details, please see the EOS/ESD chapter of the ADI Reliability Handbook (available via the 'Quality and Reliability' link on Analog Devices' web site).

Table 4: AD8417-2 ESD Test Results

ESD Model	Package	ESD Test Spec	RC Network	Highest Pass Level	First Fail Level	Class
FICDM	10-WLCSP	JS-002	1Ω, Cpkg	±1250V	NA	СЗ
НВМ	10-WLCSP	ESDA/JEDEC JS-001	1.5kΩ, 100pF	±3000V	±3500V	2

Latch-Up Test Results

Three samples of the AD8417-2 were latch-up tested at T_A =25°C per JEDEC Standard JESD78, Class I. All pins passed.

Passing Positive Current	Passing Negative Current	Passing Over-Voltage
+200mA	-200mA	+8.25V

Approvals

Reliability Engineer: Leo Ouano

Additional Information

Data sheets and other additional information are available on Analog Devices' web site